



# STB15N80K5, STF15N80K5, STP15N80K5, STW15N80K5

N-channel 800 V, 0.3 Ω typ., 14 A SuperMESH™5 Power MOSFET  
in D<sup>2</sup>PAK, TO-220FP, TO-220 and TO-247 packages

Datasheet — preliminary data

## Features

Type	V <sub>DSS</sub>	R <sub>DS(on)max</sub>	I <sub>D</sub>	P <sub>W</sub>
STB15N80K5	800 V	< 0.375 Ω	14 A	190 W
STF15N80K5				35 W
STP15N80K5				190 W
STW15N80K5				

- Worldwide best FOM (figure of merit)
- Ultra low gate charge
- 100% avalanche tested
- Zener-protected

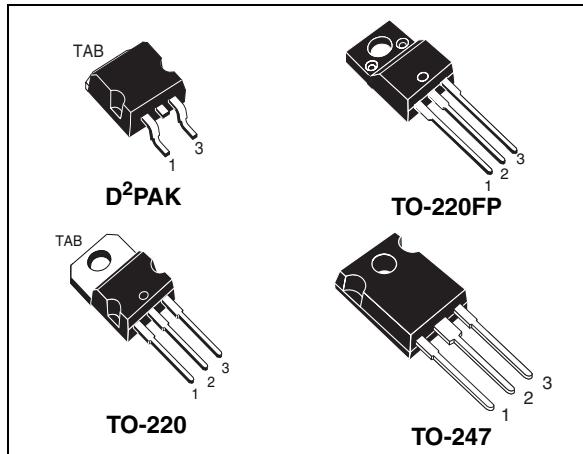


Figure 1. Internal schematic diagram

AM01476v1

Table 1. Device summary

Order codes	Marking	Package	Packaging
STB15N80K5	15N80K5	D <sup>2</sup> PAK	Tape and reel
STF15N80K5		TO-220FP	
STP15N80K5		TO-220	
STW15N80K5		TO-247	Tube

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		D <sup>2</sup> PAK, TO-220, TO-247	TO-220FP	
V <sub>GS</sub>	Gate- source voltage	± 30		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	14	14 <sup>(1)</sup>	A
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	8.8	8.8 <sup>(1)</sup>	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	56	56 <sup>(1)</sup>	A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	190	35	W
I <sub>AR</sub>	Max current during repetitive or single pulse avalanche (pulse width limited by T <sub>jmax</sub> )	TBD		A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>J</sub> = 25 °C, I <sub>D</sub> =I <sub>AS</sub> , V <sub>DD</sub> = 50 V)	TBD		mJ
V <sub>iso</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t=1 s; T <sub>C</sub> =25 °C)		2500	V
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	TBD		V/ns
T <sub>j</sub> T <sub>stg</sub>	Operating junction temperature Storage temperature	-55 to 150		°C

1. Limited by package.
2. Pulse width limited by safe operating area.
3. I<sub>SD</sub> ≤ 14 A, di/dt ≤ 100 A/μs, V<sub>Peak</sub> ≤ V<sub>(BR)DSS</sub>

**Table 3. Thermal data**

Symbol	Parameter	Value				Unit
		TO-220	TO-247	D <sup>2</sup> PAK	TO-220FP	
R <sub>thj-case</sub>	Thermal resistance junction-case max	0.66			3.6	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-amb max	62.5	50		62.5	
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-pcb max			30		

1. When mounted on 1inch<sup>2</sup> FR-4 board, 2 oz Cu.

## 2 Electrical characteristics

( $T_{CASE} = 25^\circ\text{C}$  unless otherwise specified).

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage ( $V_{GS} = 0$ )	$I_D = 1 \text{ mA}$	800			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = 800 \text{ V}$ $V_{DS} = 800 \text{ V}, T_c = 125^\circ\text{C}$			1 50	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20 \text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 100 \mu\text{A}$	3	4	5	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$		0.3	0.375	$\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance			1100		pF
$C_{oss}$	Output capacitance		-	70	-	pF
$C_{rss}$	Reverse transfer capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$		2		pF
$C_{o(\text{tr})}^{(1)}$	Equivalent capacitance time related	$V_{GS} = 0, V_{DS} = 0 \text{ to } 640 \text{ V}$	-	TBD	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related		-	TBD	-	pF
$R_G$	Intrinsic gate resistance	$f = 1 \text{ MHz open drain}$	-	3	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 640 \text{ V}, I_D = 7 \text{ A}$		30		nC
$Q_{gs}$	Gate-source charge	$V_{GS} = 10 \text{ V}$	-	TBD	-	nC
$Q_{gd}$	Gate-drain charge	(see <a href="#">Figure 3</a> )		TBD		nC

1. Time related is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$
2. Energy related is defined as a constant equivalent capacitance giving the same stored energy as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time			TBD		ns
$t_r$	Rise time			TBD		ns
$t_{d(off)}$	Turn-off delay time	$V_{DD} = 400 \text{ V}, I_D = 7 \text{ A}, R_G=4.7 \Omega, V_{GS}=10 \text{ V}$ (see <i>Figure 5</i> )	-	TBD	-	ns
$t_f$	Fall time			TBD		ns

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current				14	A
$I_{SDM}$	Source-drain current (pulsed)		-		56	A
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 14 \text{ A}, V_{GS}=0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 14 \text{ A}, V_{DD}= 60 \text{ V}$		TBD		ns
$Q_{rr}$	Reverse recovery charge	$di/dt = 100 \text{ A}/\mu\text{s},$		TBD		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see <i>Figure 4</i> )	-	TBD		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 14 \text{ A}, V_{DD}= 60 \text{ V}$		TBD		ns
$Q_{rr}$	Reverse recovery charge	$di/dt=100 \text{ A}/\mu\text{s},$		TBD		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	$T_j=150^\circ\text{C}$ (see <i>Figure 4</i> )	-	TBD		A

1. Pulsed: pulse duration = 300 $\mu\text{s}$ , duty cycle 1.5%

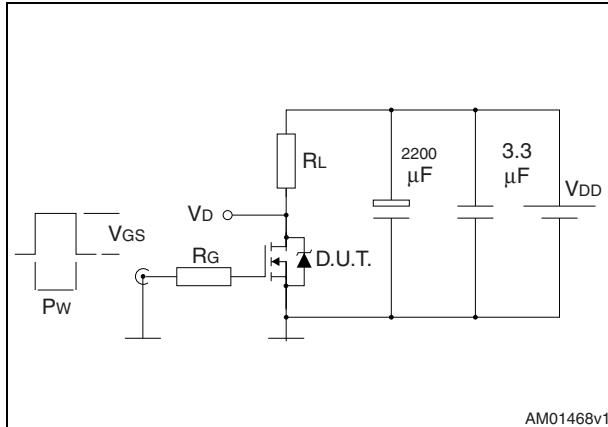
**Table 8. Gate-source Zener diode**

Symbol	Parameter	Test conditions	Min	Typ.	Max	Unit
$BV_{GSO}$	Gate-source breakdown voltage	$I_{GS} \pm 1\text{mA}, (\text{open drain})$	30	-	-	V

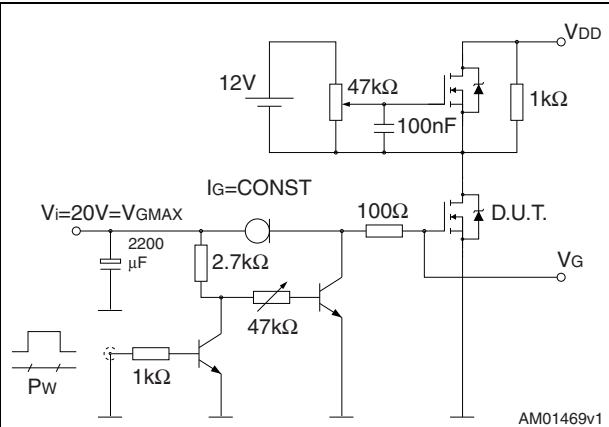
The built-in-back Zener diodes have specifically been designed to enhance not only the device's ESD capability, but also to make them safely absorb possible voltage transients that may occasionally be applied from gate to source. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.

### 3 Test circuits

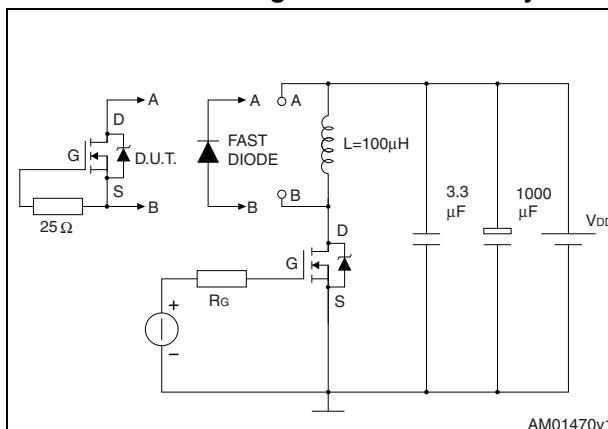
**Figure 2.** Switching times test circuit for resistive load



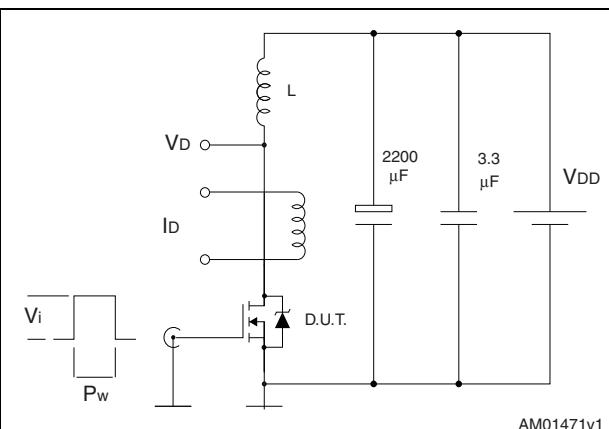
**Figure 3.** Gate charge test circuit



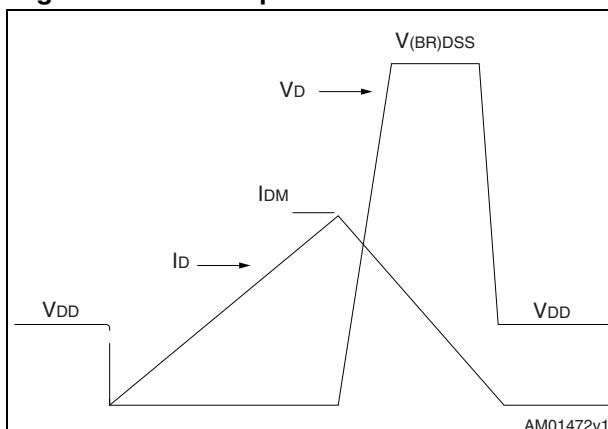
**Figure 4.** Test circuit for inductive load switching and diode recovery times



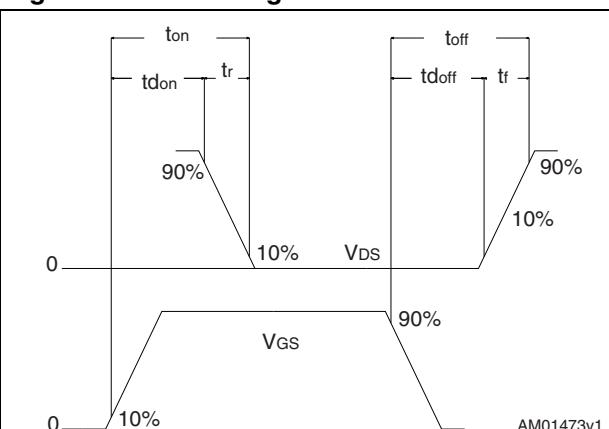
**Figure 5.** Unclamped inductive load test circuit



**Figure 6.** Unclamped inductive waveform



**Figure 7.** Switching time waveform

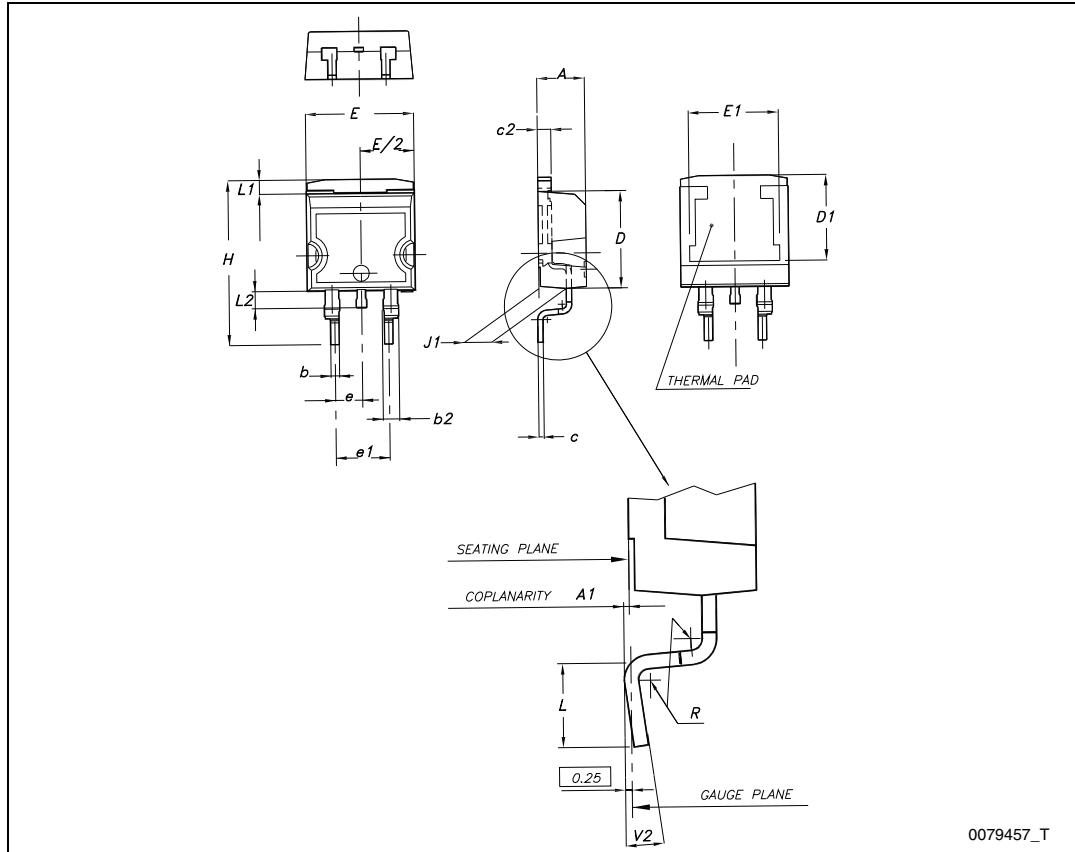
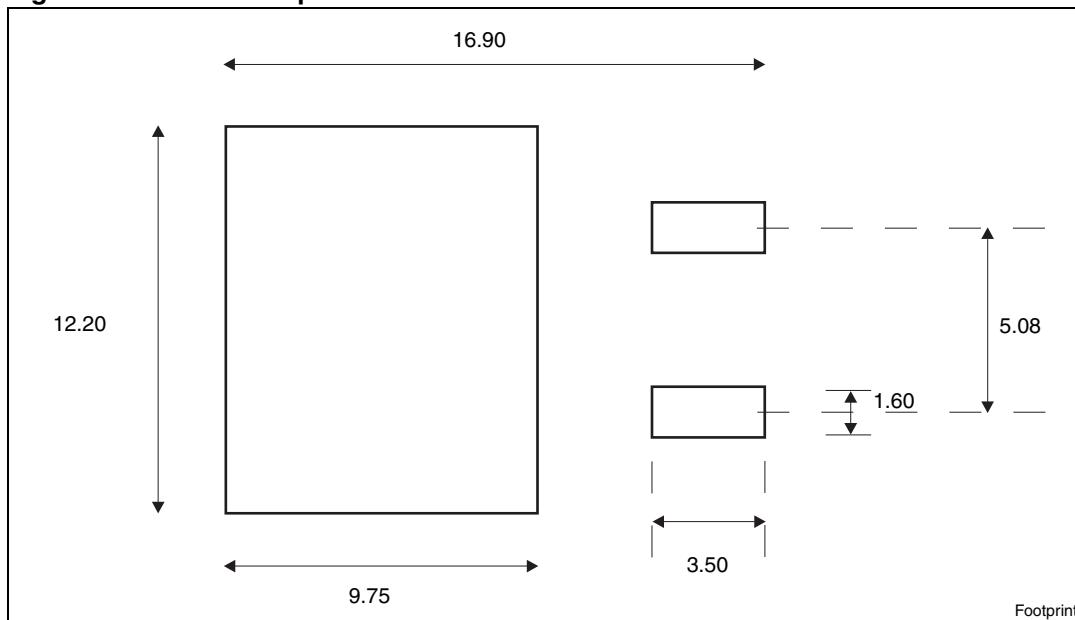


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
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**Table 9. D<sup>2</sup>PAK (TO-263) mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50		
E	10		10.40
E1	8.50		
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

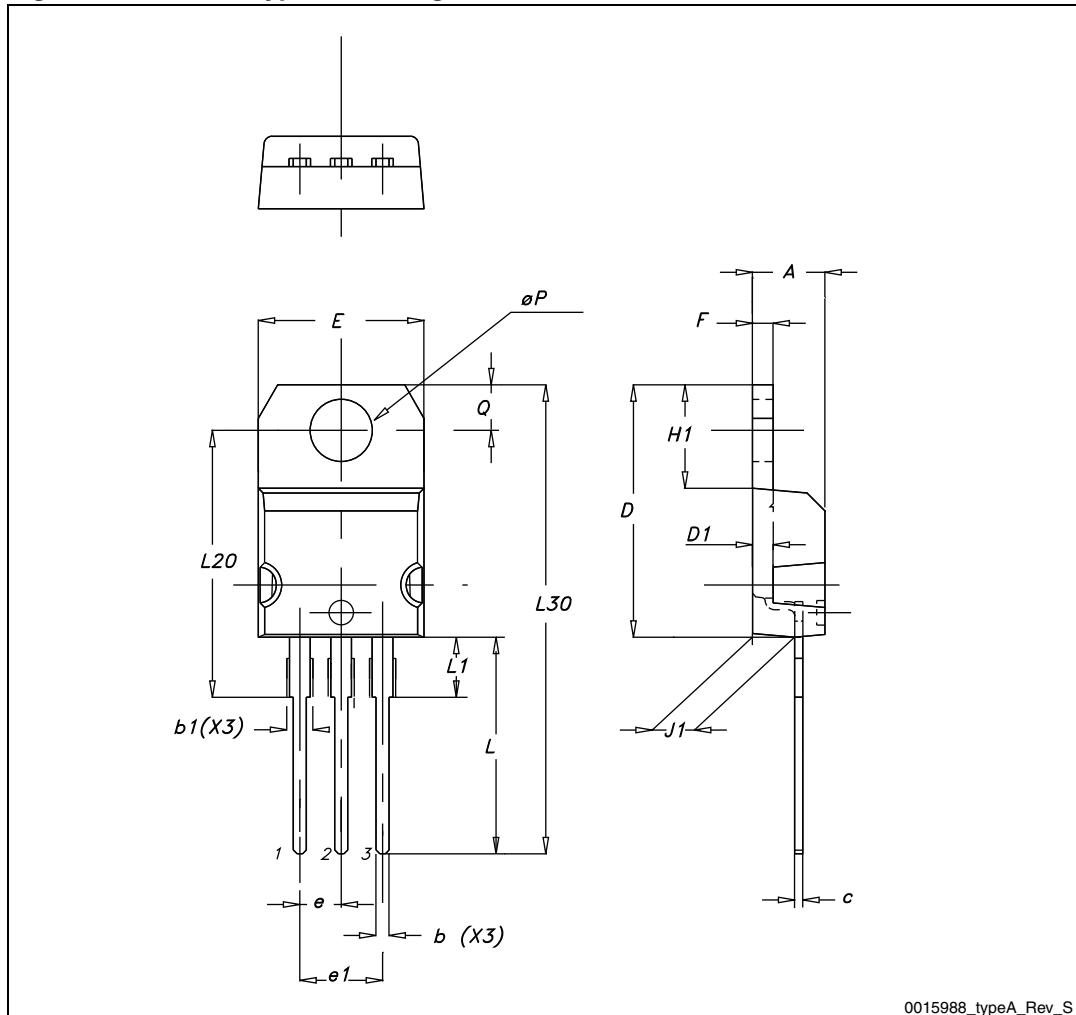
**Figure 8.** D<sup>2</sup>PAK (TO-263) drawing**Figure 9.** D<sup>2</sup>PAK footprint<sup>(a)</sup>

a. All dimension are in millimeters

**Table 10.** TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

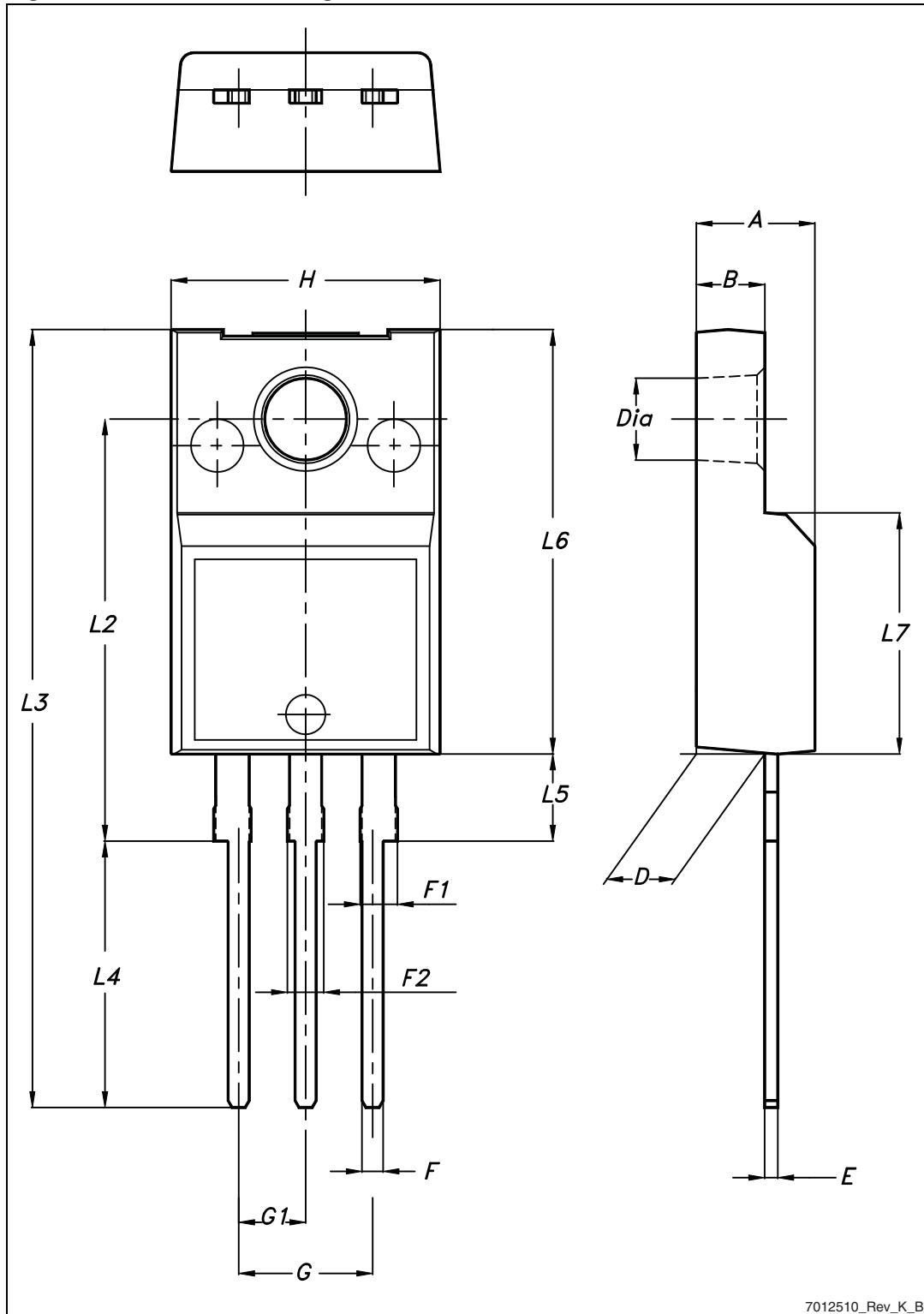
Figure 10. TO-220 type A drawing



**Table 11.** TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

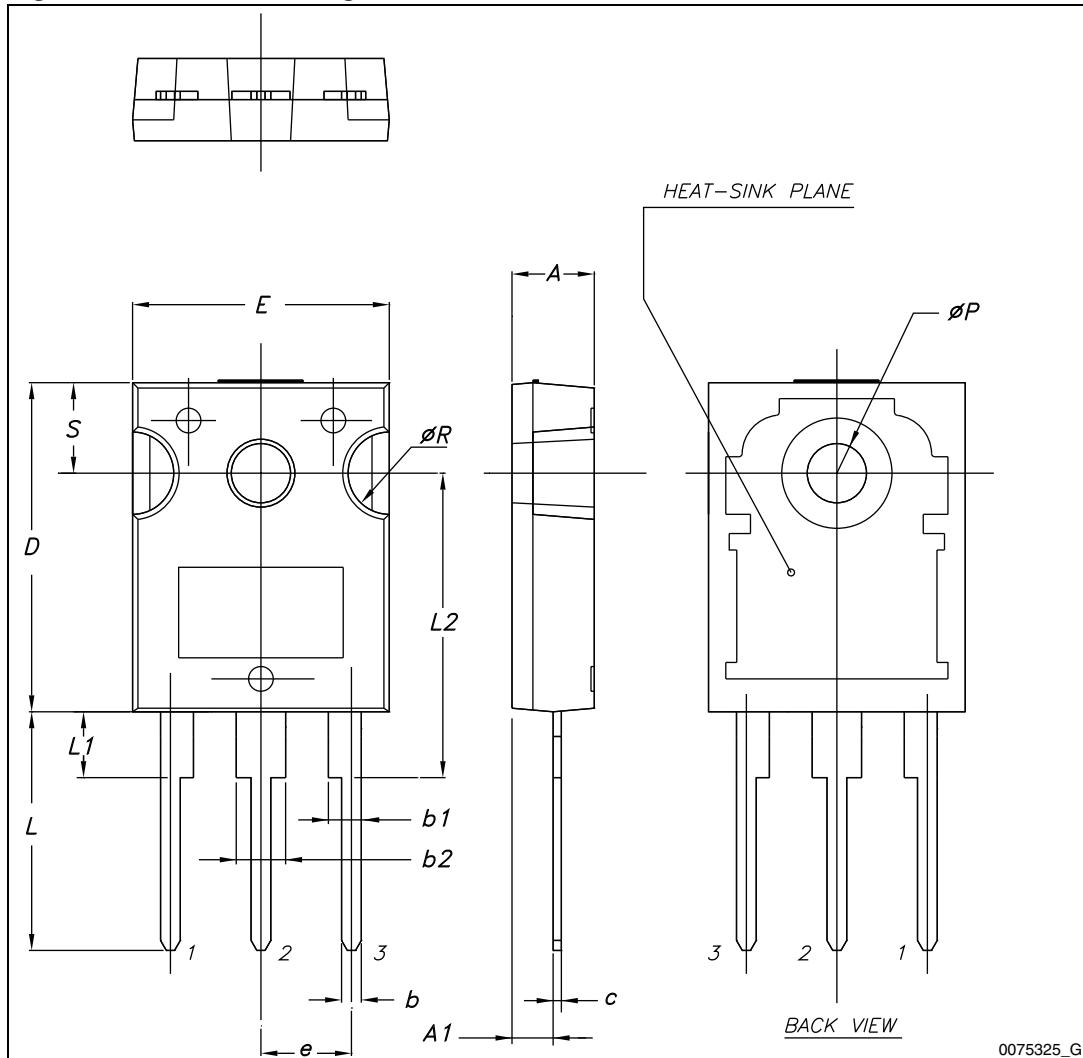
Figure 11. TO-220FP drawing



**Table 12.** TO-247 mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

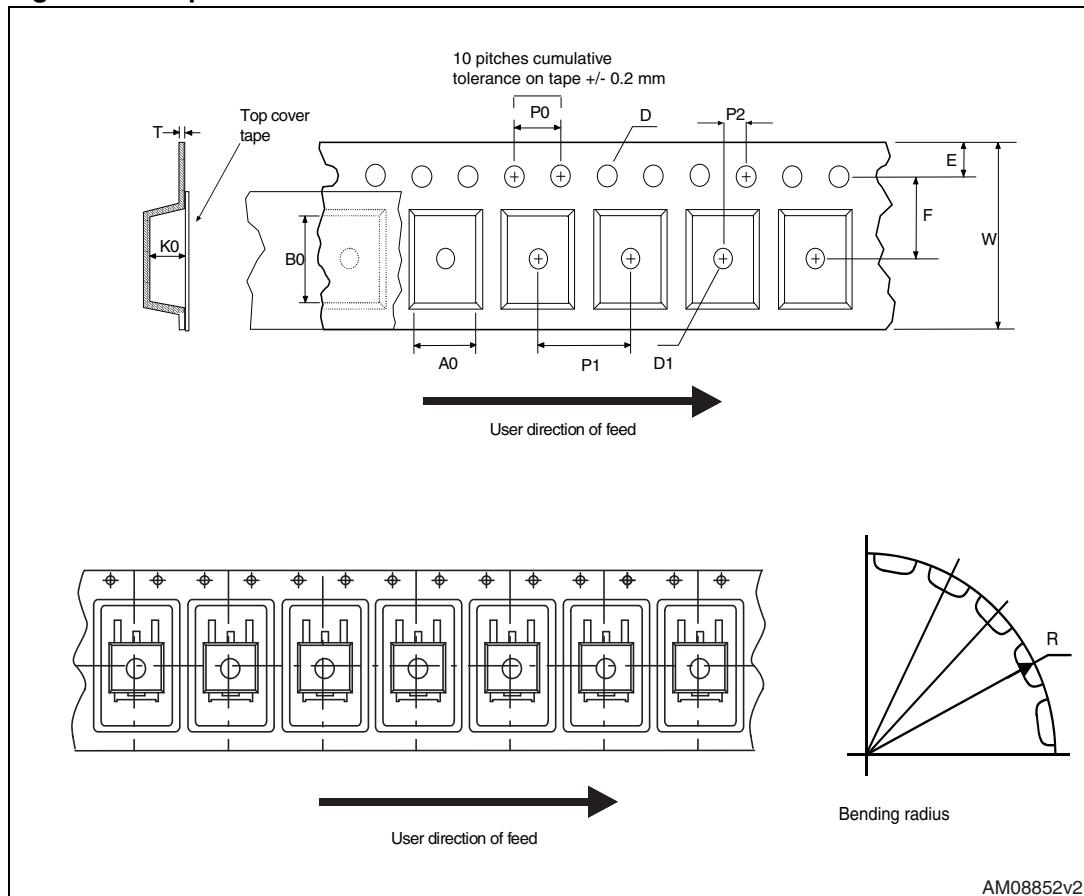
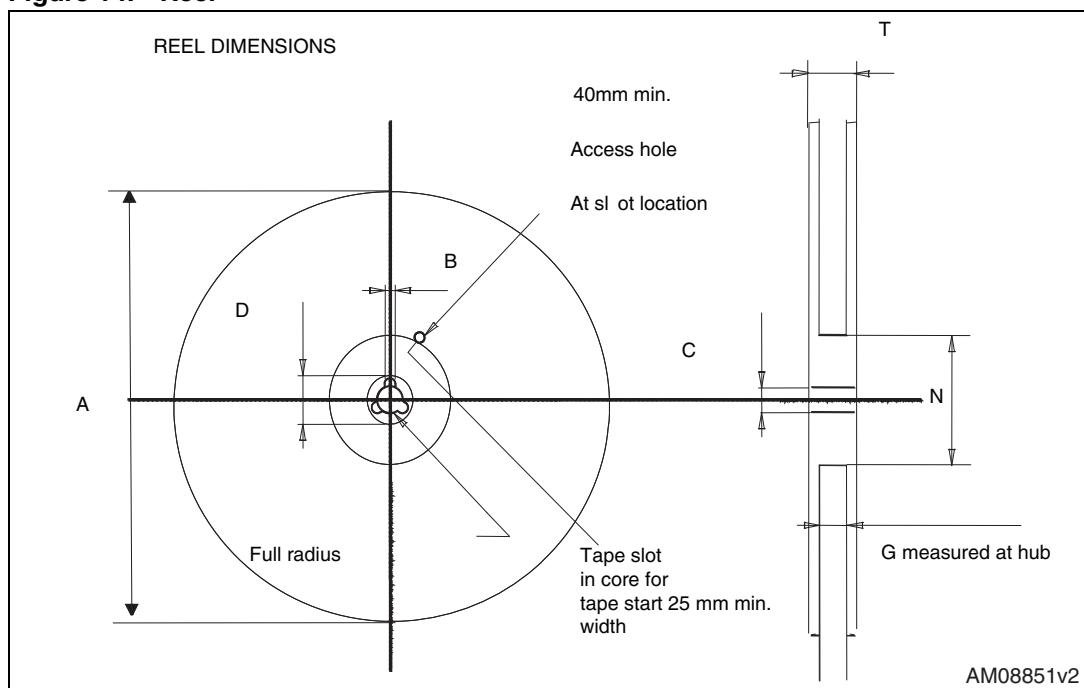
Figure 12. TO-247 drawing



## 5 Packaging information

**Table 13. D<sup>2</sup>PAK (TO-263) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty	1000
P2	1.9	2.1		Bulk qty	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

**Figure 13. Tape****Figure 14. Reel**

## 6 Revision history

**Table 14. Document revision history**

Date	Revision	Changes
18-Jul-2012	1	First release.

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